

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application:

Harry M. Haytayan

Serial No.:

10/619,374

Filing Date:

07/11/03

For:

Method And Apparatus For Fastening Together Structural

Components

Group Art Unit:

3726

Examiner:

Unknown

Attorney's Docket No.:

HMH-90 CIP

Commissioner For Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Enclosed is a Supplemental CIP Declaration And Power Of Attorney for filing in connection with the above-identified application.

The enclosed Supplemental CIP Declaration is being submitted in order to replace the Declaration which was filed with the application.

If any fees are required in connection with this matter, please charge the same to Deposit Account No. 16-0221.

Thank you.

Respectfully submitted.

Nicholas A. Pandiscio

Reg. No. 17,293 Pandiscio & Pandiscio

470 Totten Pond Road

Waltham, MA 02451-1914

Tel. (781) 290-0060

Mailing Certificate

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to the Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below:

2004.

(date of preposit)
Nicholas A. Pandiscio

(name of attorney)

bawc:letters hmh90cip.ltr



SUPPLEMENTAL CIP DECLARATION AND POWER OF ATTORNEY

As a below-named inventor, I hereby declare that: My residence, post office address and citizenship are as stated below next to my name. I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD AND APPARATUS FOR FASTENING TOGETHER STRUCTURAL COMPONENTS, the specification of which was filed on July 11, 2003, assigned Serial No. 10/619,374, and is identified by Attorney's Docket No. HMH-90 CIP.

Application Ser. No. 10/195,207, filed 15 July 2002 for "Method And Apparatus For Attaching Structural Components With Fasteners, and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56, which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56(a).

I hereby appoint Pandiscio & Pandiscio, a firm composed of Nicholas A. Pandiscio, Registration No. 17,293, Mark J. Pandiscio, Registration No. 30,883, Scott R. Foster, Registration No. 20,570, and James A. Sheridan, Registration No. 43,114, or any of them, of 470 Totten

Pond Road, Waltham, Massachusetts 02451-1914, (Telephone No. 781-290-0060), my attorneys with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent Office connected therewith.

Please direct all correspondence in this matter to:

Nicholas A. Pandiscio Pandiscio & Pandiscio, P.C. 470 Totten Pond Road Waltham, MA 02451-1914

Tel.: 781 290 0060 Fax: 781 290 4840

Please direct all telephone calls to: Nicholas A. Pandiscio or Mark J. Pandiscio

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Inventor's signature:

Inventor's full name:

HARRY M. HAYTAYAN

Date:

<u>4/30</u>, 2004

Residence:

32 Indian Rock Road

Nashua, NH 03063

Postal Address:

same

Citizenship:

U.S.A.

bawc:patforms hmh90cip.dec